

Abstract

An interconnect is provided for making electrical connections with a semiconductor die. The interconnect includes a substrate having integrally formed contact members, configured to electrically contact corresponding contact locations on the die. The interconnect also includes a pattern of conductors formed separately from the substrate, and then bonded to the substrate, in electrical communication with the contact members. The conductors can be mounted to a multi layered tape similar to TAB tape, or alternately bonded directly to the substrate. In addition, each conductor can include an opening aligned with a corresponding contact member, and filled with a conductive material, such as a conductive adhesive or solder. The conductive material electrically connects the contact members and conductors, and provides an expansion joint to allow expansion of the conductors without stressing the contact members. Also provided are a system for testing dice that includes the interconnect, and a system for testing wafers wherein the interconnect is formed as a probe card.

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